C1-C3 monovalent organic group, X_1 in General Formula (3) represents an oxygen atom, a sulfur atom, a sulfonyl group, a C1-C3 divalent organic group, or a divalent crosslink formed of two or more C1-C3 divalent organic groups bound together, and X_2 in General Formula (6) represents a direct bond, an oxygen atom, a sulfur atom, a sulfonyl group, C1-C3 divalent organic groups, or a divalent crosslink formed of two or more organic groups selected from an arylene group bound together.

[0018b]

In another aspect, there is provided a photosensitive resin composition comprising the resin as defined above.

[0018c]

In another aspect, there is provided a photosensitive resin composition comprising: (a) a resin as defined above; (b) a photo acid generator; and (c) a solvent, the photosensitive resin composition having a positive photosensitivity.

[0018d]

In another aspect, there is provided a method of producing a heat-resistant resin film from the photosensitive resin composition as defined above, comprising:

applying the photosensitive resin composition to a support substrate and drying the photosensitive resin composition to obtain a photosensitive resin film;

exposing the photosensitive resin film obtained in the step to light;

developing the exposed photosensitive resin film by using an alkaline aqueous solution; and

treating the developed photosensitive resin film with heat.

[0018e]

In another aspect, there is provided an interlayer dielectric film which is obtained by the method as defined above.

[0018f]

In another aspect, there is provided an interlayer dielectric film for a multilayer wiring structure, which has a total thickness of 10 μm or more and 50 μm or less and which is obtained by the method as

2. A photosensitive resin composition comprising the resin according claim 1.

3. A photosensitive resin composition comprising: (a) a resin according to claim 1; (b) a photo acid generator; and (c) a solvent, the photosensitive resin composition having a positive photosensitivity.

4. The resin according to claim 1 or the photosensitive resin composition according to claim 2 or 3, wherein R^2 in General Formula (1) further contains an aliphatic organic group.